

1 **IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

2 Application Serial No. .... 09/961,114 *10/1  
7 Sept 03*  
3 Filing Date ..... 09/20/2001 *7-16-03*  
4 Inventor ..... Perino et al.  
5 Group Art Unit ..... 2833  
6 Examiner ..... Figueroa, Felix O  
7 Attorney's Docket No. ..... RB1-035USC3  
8 Title: ..... Chip Socket Assembly and Chip File Assembly for Semiconductor Chips

9 **AMENDMENT AND RESPONSE TO OFFICE ACTION**  
10 **DATED APRIL 16, 2003**

11 To: Box Non-Fee Amendment  
12 Commissioner for Patents  
13 P.O. Box 1450  
14 Alexandria, VA 22313-1450

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JUL 10 2003

TECHNOLOGY CENTER 2800

15 From: Kenneth Paley  
16 Customer No. 29150  
17 Lee & Hayes PLLC  
18 421 W Riverside Ave Suite 500  
19 Spokane, WA 99201

Dear Sir:

16 This is a reply under 37 CFR § 1.114 to a final Office Action mailed April  
17 16, 2003, for the above identified application. Claims 68, 70-75, 77, 79-83 and 85-  
18 88 are pending and have been rejected. Claims 89-90 have been withdrawn.

19 Claims 68, 79, 87, and 88 are herein canceled. Claims 74, 77, 80, 81, 85, 86  
20 are herein amended. Claims 91-97 are herein added.

21 00000002 120759 09961114  
01 FC:1202 The Applicants request that the Examiner enter the following amendments,  
22 54.00 DA  
23 and consider the following remarks.